

SML032RGB1T

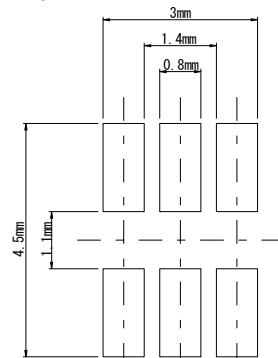
Surface Mount Chip LEDs

This product was developed as a surface mount LED especially suitable for soldering. Please take care of following points when using this device.

1. DESIGNING OF PCB

As for a recommendable solder pattern, Please refer to Fig-1.

The size and direction of the pad pattern depends on the condition of the PCB, So, please investigate about the adjustment thoroughly before designing.



(Fig-1)

2. MOUNTING

This LED was designed to fit various mounting machines.

A round type nozzle is recommended for a hollow lens surface.

3. SOLDERING (Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu)

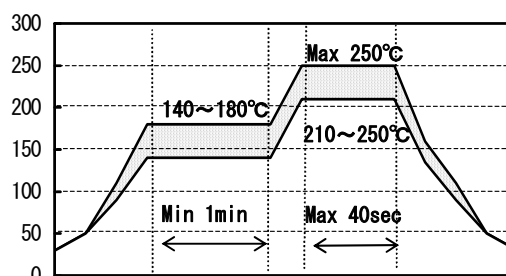
LED products do not contain reinforcement materials such as glass fillers.

Therefore, thermal stress by soldering greatly influences its reliability.

The temperature condition for reflow soldering should therefore be set up according to the characteristic of this products. (See Fig.2)

Number of reflow process shall be max 2 times and these processes should be performed in a row.

Cooling process to normal temp. Shall be required between the first and the second soldering process.



(Fig-2)

4. WASHING

Please note the following points when washing is required after soldering.

4-1) WASHING SOLVENT

Isopropyl alcohol or other alcohol solvent is recommendable.

4-2) TEMPERATURE

Below 30°C, immersion time : within 3 minutes.

4-3) ULTRA SONIC WASHING

Below 15W / 1 liter of solvent tub.

4-4) COOLING

Below 100°C within 3 minutes.

5. STORAGE

At reflow soldering, the reliability of this product is often influenced by moisture absorption so we apply the packaging with moisture proof for better condition of use ; please also note that

5-1) The package is not to be opened before using when storing.

5-2) LED to be kept in our moisture proof packaging with some desiccant (SILICA GEL) after opening it.

LED to be baked in case the SILICA GEL indicator changed its color from either blue to clear or green to pink.

5-3) Please use LED within 168 hours after the package is opened. (Condition ; below 30°C, max.70%Rh.)

In case it is not used within 168 hours, please put it back into our packaging.

5-4) BAKING

Please bake under reel condition at 60°C, 12~24 hours (max.20%Rh) after unsealing.

While baking is done, the reel and emboss tape may be easily deformed.

Please be careful not to give any stress.